

1.0A Avg.

60 Volts

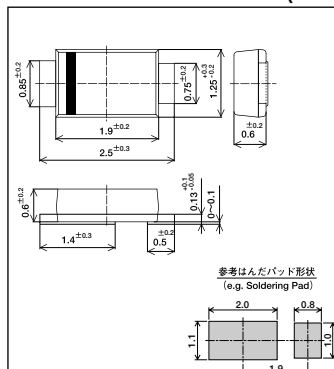
SBD

SA10QA06

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	60	V
直流順電流 Direct Forward Current	I_{DC}	直流通電 Direct Current $T_a=54^{\circ}\text{C}^{*1}$	1.41 A
平均整流電流 Average rectified Forward Current	I_o	方形波通電 RECT 180°C Rectangular Wave 50% Duty $T_a=56^{\circ}\text{C}^{*1}, V_{RM}=30\text{V}$ $T_l=117^{\circ}\text{C}, V_{RM}=30\text{V}$ (T_l : Lead Temperature)	1.0 A
サージ順電流 Surge Forward Current	I_{FSM}	20 (50Hz正弦半波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	$-40\sim+150$	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	$-40\sim+150$	$^{\circ}\text{C}$

OUTLINE DRAWING(mm)



APPROX. NET WEIGHT:0.004 g

電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$V_{RM}=5\text{V}$ $T_a=25^{\circ}\text{C}$	—	0.3	—	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$V_{RM}=60\text{V}$ $T_a=25^{\circ}\text{C}$ $I_{FM}=0.7\text{A}$ $T_a=25^{\circ}\text{C}$ $I_{FM}=1.0\text{A}$ $T_a=25^{\circ}\text{C}$	—	0.55	0.58	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 (Junction to Ambient) *1 (アルミナ基板実装) *2 (ガラエポ基板実装)	—	—	100	$^{\circ}\text{C/W}$
	$R_{th(j-l)}$	接合部・リード間 (Junction to Lead)	—	—	30	$^{\circ}\text{C/W}$

*1: プリント基板実装/Alumina Substrate Mounted (Soldering Land=6×6mm)

*2: プリント基板実装/Glass-Epoxy Substrate Mounted (Soldering Land=6×6mm)

定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

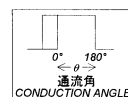
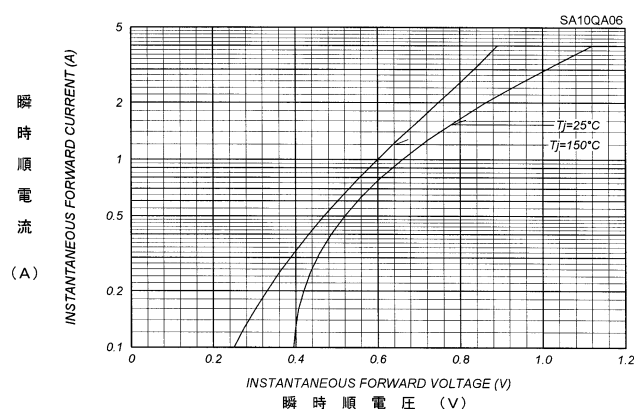


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

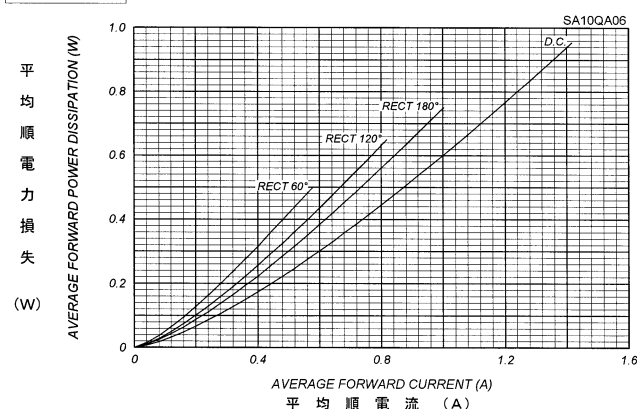


FIG.3
ピーク逆電流 - ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE
 $T_j=150^{\circ}\text{C}$

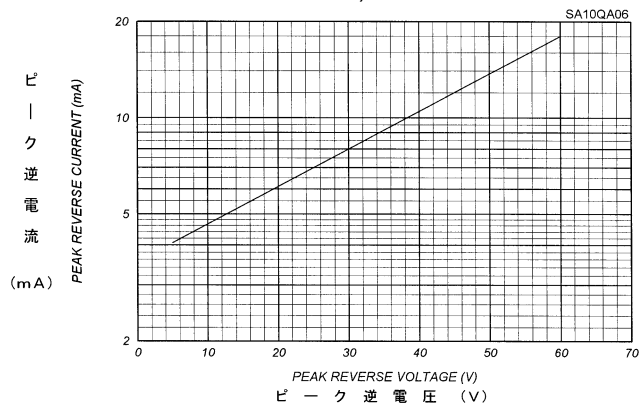
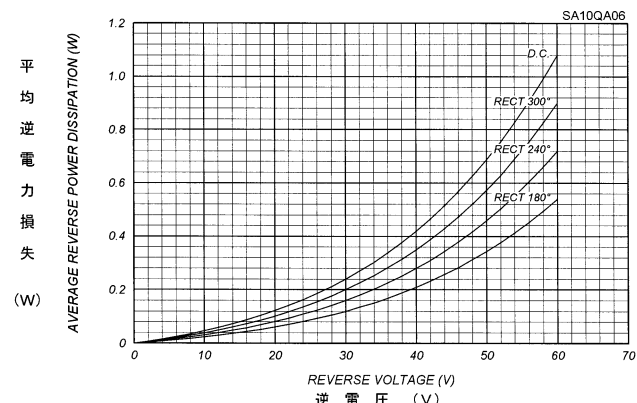


FIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION



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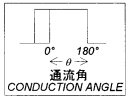


FIG.5

平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Alumina substrated Mounted, $V_{RM}=30V$

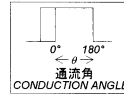
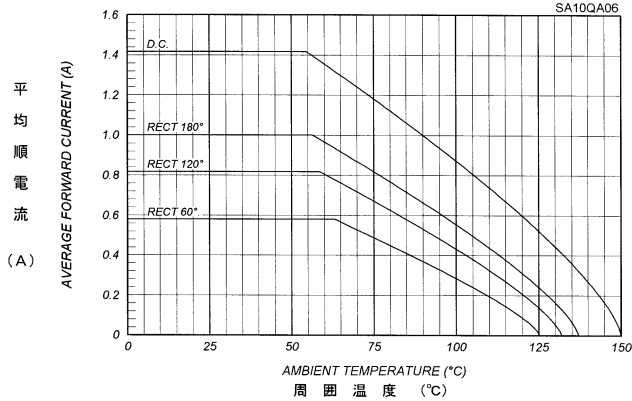


FIG.6

平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy substrated Mounted, $V_{RM}=30V$

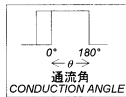
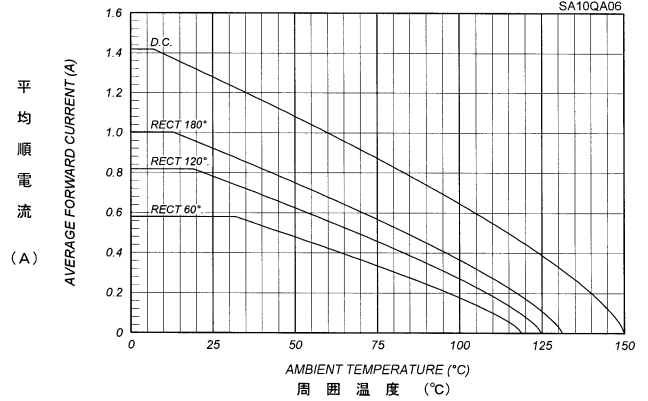


FIG.7

平均順電流－リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE
 $V_{RM}=30V$

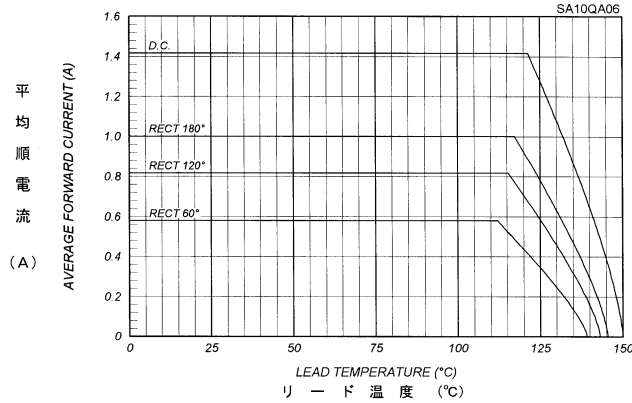


FIG.8

サージ順電流定格
SURGE CURRENT RATINGS
 $f=50Hz$, Half Sine Wave, Non-Repetitive, No Load

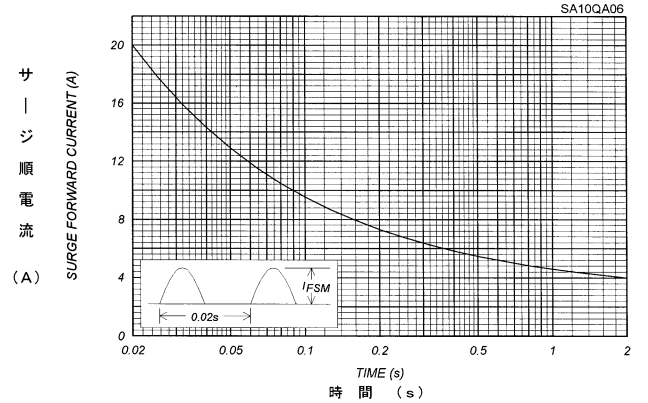


FIG.9

接合容量特性
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE
 $T_J=25^{\circ}C$, $V_m=20mV$, $f=100kHz$, Typical Value

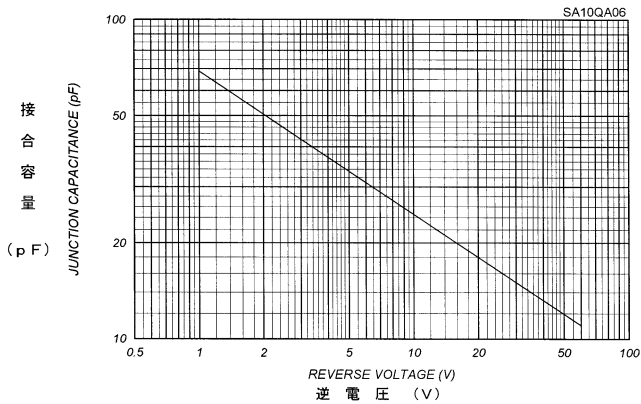


FIG.10

過渡熱抵抗特性
Transient Thermal Impedance

